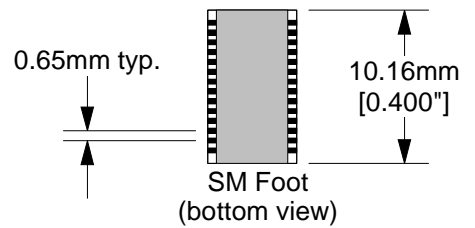
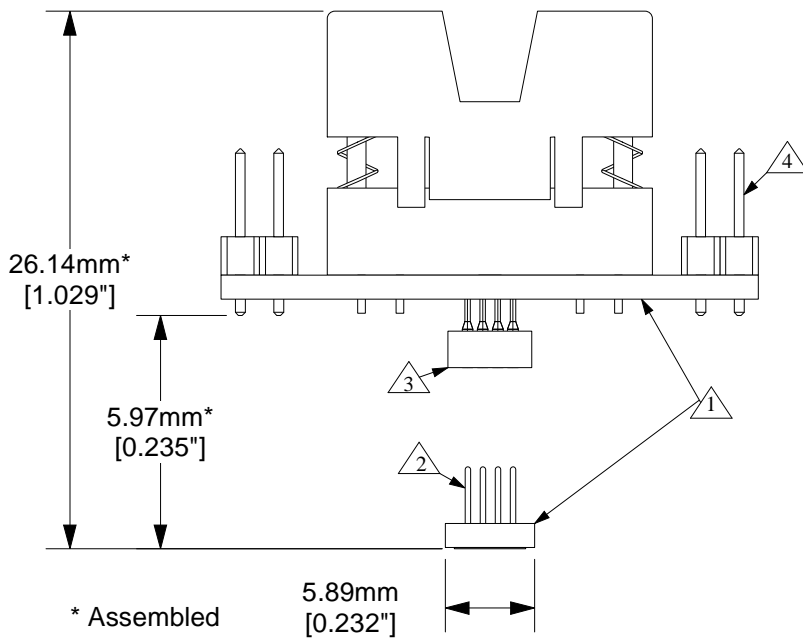


Side View




- ① Substrate: 0.0625"±0.007" FR4/G10 or equivalent high temp material. 1/2 oz. Cu clad. SnPb plating
- ② Pins: Material- Brass Alloy 360 1/2 hard; finish- 10µ" Au over 50µ" Ni (min.).
- ③ Pins: shell material- Brass Alloy 360 1/2 hard; finish- 10µ" Au over 50µ" Ni (min.). Contact material- BeCu; finish 10µ" Au over 100µ" Ni (min.).
- ④ Test points: material- Phosphor Bronze; plating- Sn over 50µ" Ni. Gold flash on contact end.

Description: Carrier Adaptor, SOIC

28 position ZIF socket with test points to 28 position surface mount foot (bottom termination). Two piece assembly has gold plated pluggable interface between socket and foot assemblies.

Tolerances: diameters ±0.03mm [±0.001"], PCB perimeters ±0.13mm [±0.005"], PCB thicknesses ±0.18mm [±0.007"], pitches (from true position) ±0.08mm [±0.003"], all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

	CA-SO28U-Z-K-T-01 Drawing	Status: Released	Scale 2:1	Rev: B
	© 2000 IRONWOOD ELECTRONICS, INC. PO BOX 21151 ST. PAUL, MN 55121 Tele: (651) 452-8100 www.ironwoodelectronics.com	Drawing: P Jasmin		Date: 7/18/0
		File: CA-SO28U-Z-K-T-01 Dwg.mcd	Modified: 2/22/01, JC	